

LOCTITE ABLESTIK ABP 2501

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PRODUCT DESCRIPTION

LOCTITE ABLESTIK ABP 2501 provides the following product characteristics:

Technology	BMI Hybrid
Appearance	red
Product Benefits	• Non-conductive • Single component • Low temperature cure • Fast cure • Low modulus of elasticity • Good dispensing characteristics
Cure	Heat cure
Application	Die attach
Typical Package Application	Smart Card

LOCTITE ABLESTIK ABP 2501 die attach adhesive has been formulated for use in high throughput die bonding applications. This material is designed to minimize stress and resulting warpage between dissimilar surfaces. In conventional box or convection conveyor oven curing, it will cure at temperatures as low as 110°C.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Thixotropic Index (0.5/5 rpm)	4.0
Viscosity, Brookfield CP51, 25 °C, mPa·s (cP):	
Speed 5 rpm	10,500
Work Life @ 25°C, hours	24
Shelf Life @ -40°C (from date of manufacture), year	1

TYPICAL CURING PERFORMANCE

Cure Schedule

90 seconds @ 110°C

Alternative Cure Schedule

10 seconds @ 150°C

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties

Glass Transition Temperature (Tg) by TMA, °C	121
Tensile Modulus, DMTA :	
@ -65 °C	N/mm ² 4,900 (psi) (707,500)
@ 25 °C	N/mm ² 1,430 (psi) (207,260)
@ 150 °C	N/mm ² 80 (psi) (11,310)
@ 250 °C	N/mm ² 70 (psi) (10,300)
Extractable Ionic Content, ppm:	
Chloride (Cl-)	<10
Sodium (Na+)	<10
Potassium (K+)	<10

TYPICAL PERFORMANCE OF CURED MATERIAL

Miscellaneous

Die Shear Strength:	
2 X 2 mm (80 x 80 mil) Si die:	
on Au FR4, kg-f/die	10
on Ag/Cu, kg-f/die	8
on PBGA, kg-f/die	8

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

THAWING:

1. Allow container to reach room temperature before use.
2. After removing from the freezer, set the syringes to stand vertically while thawing.
3. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
4. DO NOT re-freeze. Once thawed to 25°C, the adhesive should not be re-frozen.

DIRECTIONS FOR USE

1. Thawed adhesive should immediately be placed on dispense equipment for use.
2. If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive.
3. Adhesive must be completely used within the product's recommended work life.
4. Apply enough adhesive to achieve a 25 to 50 μm wet bondline thickness, dispensed with approximately 25 to 50 % filleting on all sides of the die.
5. Alternate dispense amounts may be used depending on the application requirements.
6. Star or crossed shaped dispense patterns will yield fewer bondline voids than the matrix style of dispense pattern.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$
 $\text{kV/mm} \times 25.4 = \text{V/mil}$
 $\text{mm} / 25.4 = \text{inches}$
 $\text{N} \times 0.225 = \text{lb}$
 $\text{N/mm} \times 5.71 = \text{lb/in}$
 $\text{N/mm}^2 \times 145 = \text{psi}$
 $\text{MPa} \times 145 = \text{psi}$
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$
 $\text{mPa}\cdot\text{s} = \text{cP}$

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation and its affiliates ("Henkel") specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel products. Henkel specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

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Reference 0.1